



## Material Content Data Sheet



<b>Sales Product Name</b>		IAUT300N08S5N014		<b>Issued</b>		1. August 2018			
<b>MA#</b>		MA001696566							
<b>Package</b>		PG-HSOF-8-1		<b>Weight*</b>		771.91 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.854	0.76	0.76	7584	7584	
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.02		163		
	non noble metal	iron	7439-89-6	0.421	0.05		545		
	non noble metal	copper	7440-50-8	420.040	54.41	54.48	544155	544863	
	non noble metal	aluminium	7429-90-5	13.901	1.80	1.80	18008	18008	
wire	non noble metal	aluminium	7429-90-5	13.901	1.80	1.80	18008	18008	
encapsulation	organic material	carbon black	1333-86-4	4.791	0.62		6207		
	plastics	epoxy resin	-	52.701	6.83		68273		
	inorganic material	silicondioxide	60676-86-0	261.907	33.93	41.38	339297	413777	
leadfinish	non noble metal	tin	7440-31-5	6.479	0.84	0.84	8393	8393	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		2		
	non noble metal	nickel	7440-02-0	0.526	0.07	0.07	681	683	
solder	non noble metal	tin	7440-31-5	0.103	0.01		134		
	noble metal	silver	7440-22-4	0.129	0.02		167		
	non noble metal	lead	7439-92-1	4.933	0.64	0.67	6391	6692	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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